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Wafer Processing Report

from **Semiconductor INTERNATIONAL**

May 25, 2007

IN THIS EDITION

NEWS

- » Inverse Woodpile Structure Has Large Photonic Band Gap
- » IBM, Chartered, Samsung, Infineon, Freescale Expand Technology Agreements
- » Intel, STMicro Establish New Flash Memory Company
- » Hynix Joins IMEC's Sub-32 nm CMOS Research Platform
- » Intel Stands Behind High-k at 45 nm and Below
- » UMC Opens R&D HQ
- » AMAT Up 13%, Receives Patents

EDITOR'S PICKS

- » CNTs Attractive Alternative for Interconnects
- » Silicides Support Advanced Gate Stacks
- » Chemistry Is Key to ECMP Efficiency
- » Webcast: Strained Silicon Update

PRODUCTS

- » Metal Hard Mask Technology
- » Plating Controller
- » Vacuum Gauge Module
- » Vibration Isolation Workstation
- » Gas Detector

UPCOMING EVENTS

Dear Subscriber,



Innovative collaboration is the order of the day, with new announcements from IBM and partners on a common platform for 32 nm, the formation of a new \$3.6B flash memory company by Intel and ST Microelectronics, and R&D collaboration between Hynix and IMEC. Remember that you can always find other useful information at our Wafer Processing Info Channel:

www.semiconductor.net/wafer

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Open up to new possibilities with Hitachi's XT etch chamber.



Last year, Hitachi launched its new XT etch chamber, designed to meet the rigorous challenges facing etch for 32nm node IC technologies. This year, the XT etch chamber has been selected by six of the top ten semiconductor and memory manufacturing companies in the world. In just one year, Hitachi has redefined the limits of etch capabilities. [Click here.](#)

NEWS

Inverse Woodpile Structure Has Large Photonic Band Gap

US States News, 5/21/2007

Researchers from the University of Illinois at Urbana-Champaign demonstrated an inverse woodpile structure with one of the widest photonic band gaps ever reported. The oddly named structure is composed of a germanium matrix containing a periodic array of tubular holes, made possible by a unique and flexible fabrication technique. [More](#)

IBM, Chartered, Samsung, Infineon, Freescale Expand Technology Agreements

Market Wire, 5/22/2007

IBM and its technology partners signed a series of semiconductor process development and manufacturing agreements. The joint development agreements between these companies will now include 32 nm bulk CMOS process technologies and joint development of process design kits. [More](#)

Intel, STMicro Establish New Flash Memory Company

Business Wire, 5/22/2007

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